12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260806000.1	PCN Issued	August 07, 2026
Qualification of TI Philippines as additional Assembly site and BOM options for select devices		Sample request deadline:	October 06, 2026
		Estimated 1st ship date:	November 05, 2026
***Sample requests received after** October 06, 2026* **will not be supported.**			

Change type(s)
Assembly Site Assembly Process Assembly Material Packing/Shipping/Labeling

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of TI Philippines as additional Assembly Site for selected devices as listed below in the product affected section.

Construction Differences are as follows:

	Current	Additional
Assembly Site	HNA	PHI
Lead Finish	NiPdAu	Matte Sn
Bond Wire	Au, 0.8mil	Cu, 0.8mils
Mold Compound	SID#450214	4222198
Mount Compound	SID#400194	4226215

Qual details are provided in the Qual Data Section.

Reason for Change:	Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability:	• Physical aspects of the device have changed • Device quality has improved • Request the Supporting Data Packet for more details on the changes
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site Information

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
HANA Thailand	HNT	THA	Ayutthaya
TI Philippines	**PHI**	**PHL**	**Baguio City**

Sample product shipping label (not actual product label):

Products Affected:			
SN74AUP1G04DRLR	SN74AUP1G08DRLR	SN74AUP1G125DRLR	SN74AUP1G126DRLR
SN74AUP1G14DRLR	SN74AUP1G34DRLR		

Qualification Report

TIPI 5DRL Offload
Approve Date 22-June -2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AUP1G08DRLR	QBS Package Reference: OPA4991QDYYRQ1	QBS Process Reference: TS3USB221AQRSERQ1	QBS Package Reference: TMP112AQDRLRQ1
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	3/231/0	-	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	-	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	1/77/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	1/15/0

Type	#	Test Name	Condition	Duration	Qual Device: SN74AUP1G08DRLR	QBS Package Reference: OPA4991QDYYRQ1	QBS Process Reference: TS3USB221AQRSERQ1	QBS Package Reference: TMP112AQDRLRQ1
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	1/10/0
FTY	E6	Final Test Yield	-	-	1/All/0	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74AUP1G08DRLR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2512-013

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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